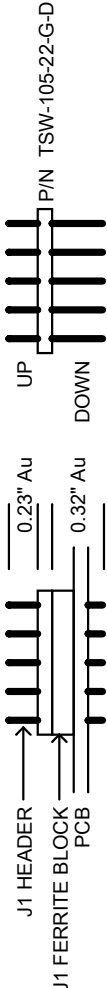
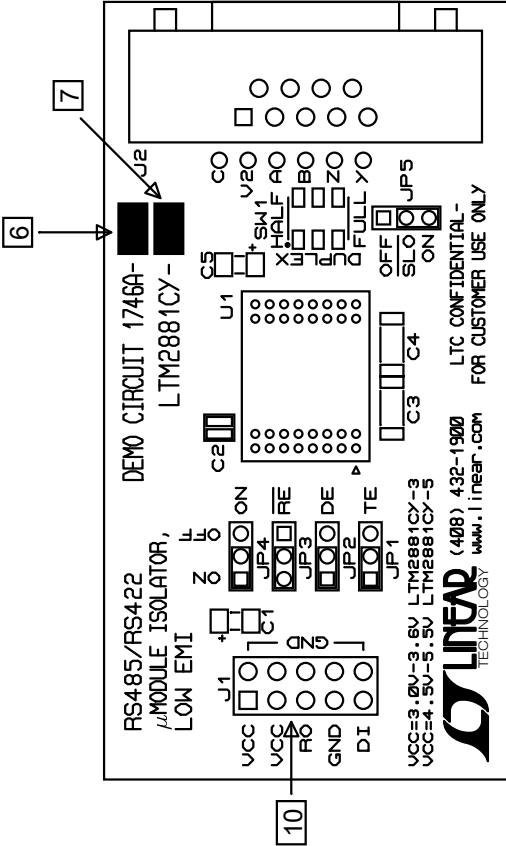


REVISION HISTORY				
ECO	REV	DESCRIPTION	APPROVED	DATE
-	1	1ST PROTOTYPE	KEITH B.	08-16-10


NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610
2. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS
3. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD
4. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
5. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD
6. MARK ASSEMBLY TYPE WITH BLACK PERMANENT MARKER WHERE SHOWN
7. MARK IC PART NUMBER WITH BLACK PERMANENT MARKER WHERE SHOWN
8. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD
9. INSTALL SHUNTS AS SHOWN
10. PLACE FERRITE BLOCK ON LONG SIDE HEADER PINS BEFORE BOARD INSERTION



P/N 2644247101

ASSY	U1
-A	LTM2881CY-3
-B	LTM2881CY-5

APPROVALS		LTC CONFIDENTIAL FOR CUSTOMER USE ONLY	
PCB DES.	KEITH B.	<div>  </div>	
APP ENG.	KEITH B.		
TITLE: SCHEMATIC		RS485/RS422 uMODULE ISOLATOR, LOW EMI	
SIZE	N/A	IC NO.	REV.
		LTM2881CY-3/-5	1
		DEMO CIRCUIT 1746A	
SCALE = 1.5:1	DATE: Tuesday August 16, 2010	SHEET 1 OF 1	